

TECNICAS DIGITALES I

KIT CPLD

XC9572XL

Kit de desarrollo



Características Eléctricas

Absolute Maximum Ratings⁽²⁾

Symbol	Description	Value	Units
V _{CC}	Supply voltage relative to GND	-0.5 to 4.0	V
V _{IN}	Input voltage relative to GND ⁽¹⁾	-0.5 to 5.5	V
V _{TS}	Voltage applied to 3-state output ⁽¹⁾	-0.5 to 5.5	V
T _{STG}	Storage temperature (ambient) ⁽³⁾	-65 to +150	°C
T _J	Junction temperature	+150	°C

Notes:

1. Maximum DC undershoot below GND must be limited to either 0.5V or 10 mA, whichever is easier to achieve. During transitions, the device pins may undershoot to -2.0 V or overshoot to +7.0V, provided this over- or undershoot lasts less than 10 ns and with the forcing current being limited to 200 mA. External I/O voltage may not exceed V_{CCINT} by 4.0V.
2. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.
3. For soldering guidelines and thermal considerations, see the [Device Packaging](#) information on the Xilinx website. For Pb-free packages, see [XAPP427](#).

Recommended Operation Conditions

Symbol	Parameter		Min	Max	Units
V _{CCINT}	Supply voltage for internal logic and input buffers	Commercial T _A = 0°C to 70°C	3.0	3.6	V
		Industrial T _A = -40°C to +85°C	3.0	3.6	V
V _{CCIO}	Supply voltage for output drivers for 3.3V operation		3.0	3.6	V
	Supply voltage for output drivers for 2.5V operation		2.3	2.7	V
V _{IL}	Low-level input voltage		0	0.80	V
V _{IH}	High-level input voltage		2.0	5.5	V
V _O	Output voltage		0	V _{CCIO}	V

Reprogramación y Condiciones de operación

Quality and Reliability Characteristics

Symbol	Parameter	Min	Max	Units
T_{DR}	Data Retention	20	-	Years
N_{PE}	Program/Erase Cycles (Endurance)	10,000	-	Cycles
V_{ESD}	Electrostatic Discharge (ESD)	2,000	-	Volts

DC Characteristic Over Recommended Operating Conditions

Symbol	Parameter	Test Conditions	Min	Max	Units
V_{OH}	Output high voltage for 3.3V outputs	$I_{OH} = -4.0 \text{ mA}$	2.4	-	V
	Output high voltage for 2.5V outputs	$I_{OH} = -500 \text{ }\mu\text{A}$	90% V_{CCIO}	-	V
V_{OL}	Output low voltage for 3.3V outputs	$I_{OL} = 8.0 \text{ mA}$	-	0.4	V
	Output low voltage for 2.5V outputs	$I_{OL} = 500 \text{ }\mu\text{A}$	-	0.4	V
I_{IL}	Input leakage current	$V_{CC} = \text{Max}; V_{IN} = \text{GND or } V_{CC}$	-	± 10	μA
I_{IH}	I/O high-Z leakage current	$V_{CC} = \text{Max}; V_{IN} = \text{GND or } V_{CC}$	-	± 10	μA
I_{IH}	I/O high-Z leakage current	$V_{CC} = \text{Max}; V_{CCIO} = \text{Max}; V_{IN} = \text{GND or } 3.6\text{V}$	-	± 10	μA
		$V_{CC} \text{ Min} < V_{IN} < 5.5\text{V}$	-	± 50	μA
C_{IN}	I/O capacitance	$V_{IN} = \text{GND}; f = 1.0 \text{ MHz}$	-	10	pF
I_{CC}	Operating supply current (low power mode, active)	$V_{IN} = \text{GND}, \text{ No load}; f = 1.0 \text{ MHz}$	20 (Typical)		mA

Arquitectura del CPLD

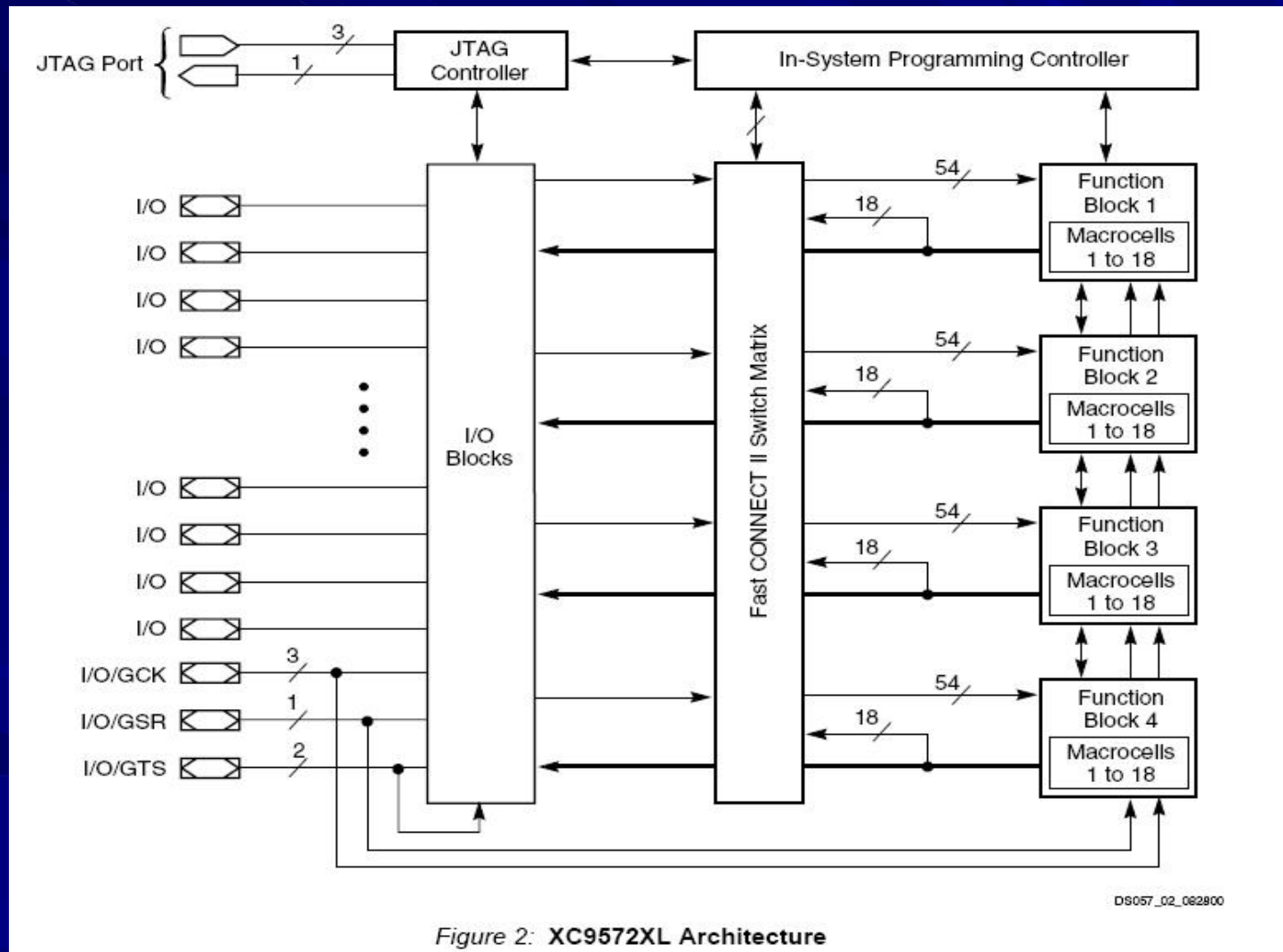
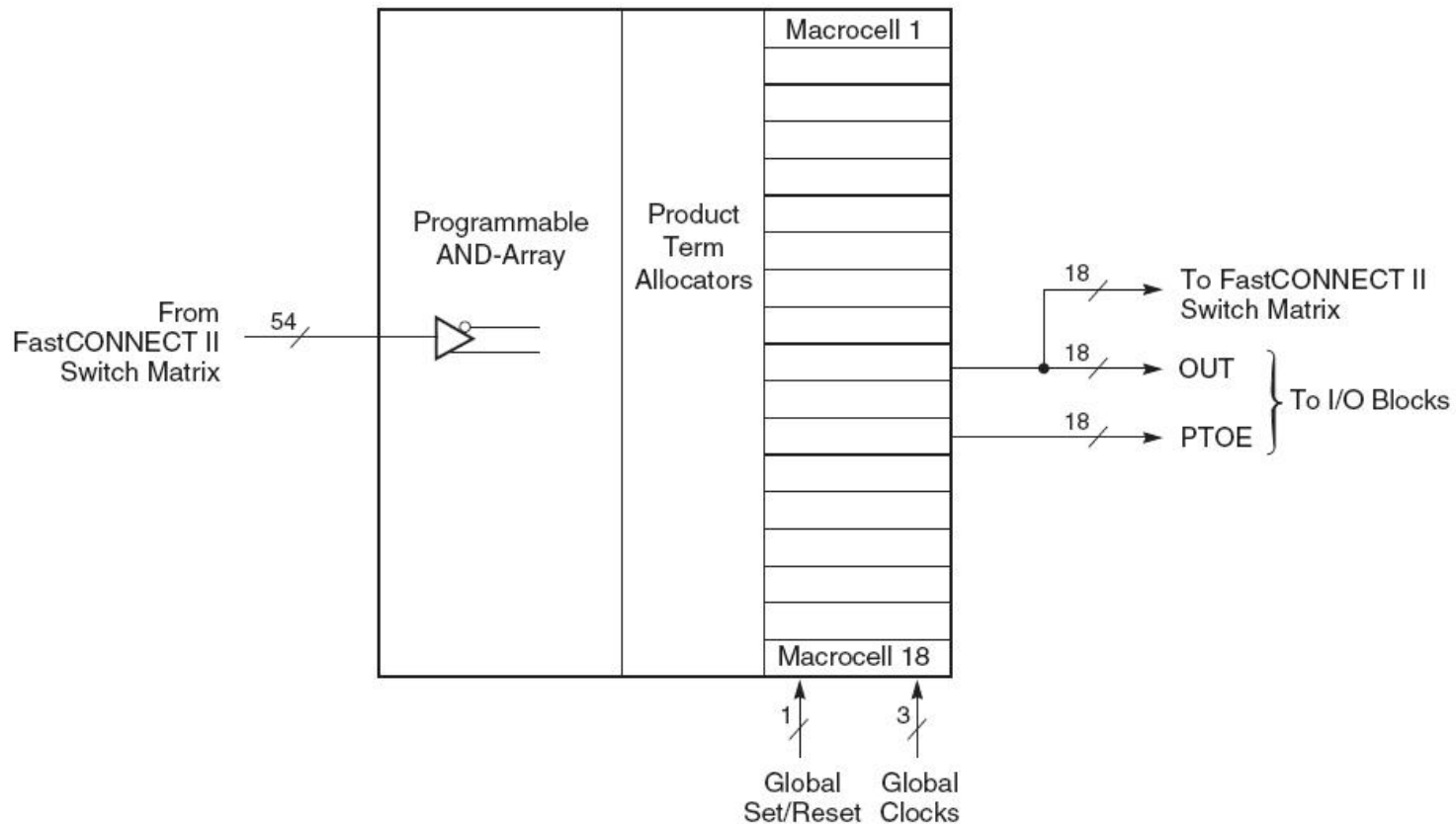


Figure 2: XC9572XL Architecture

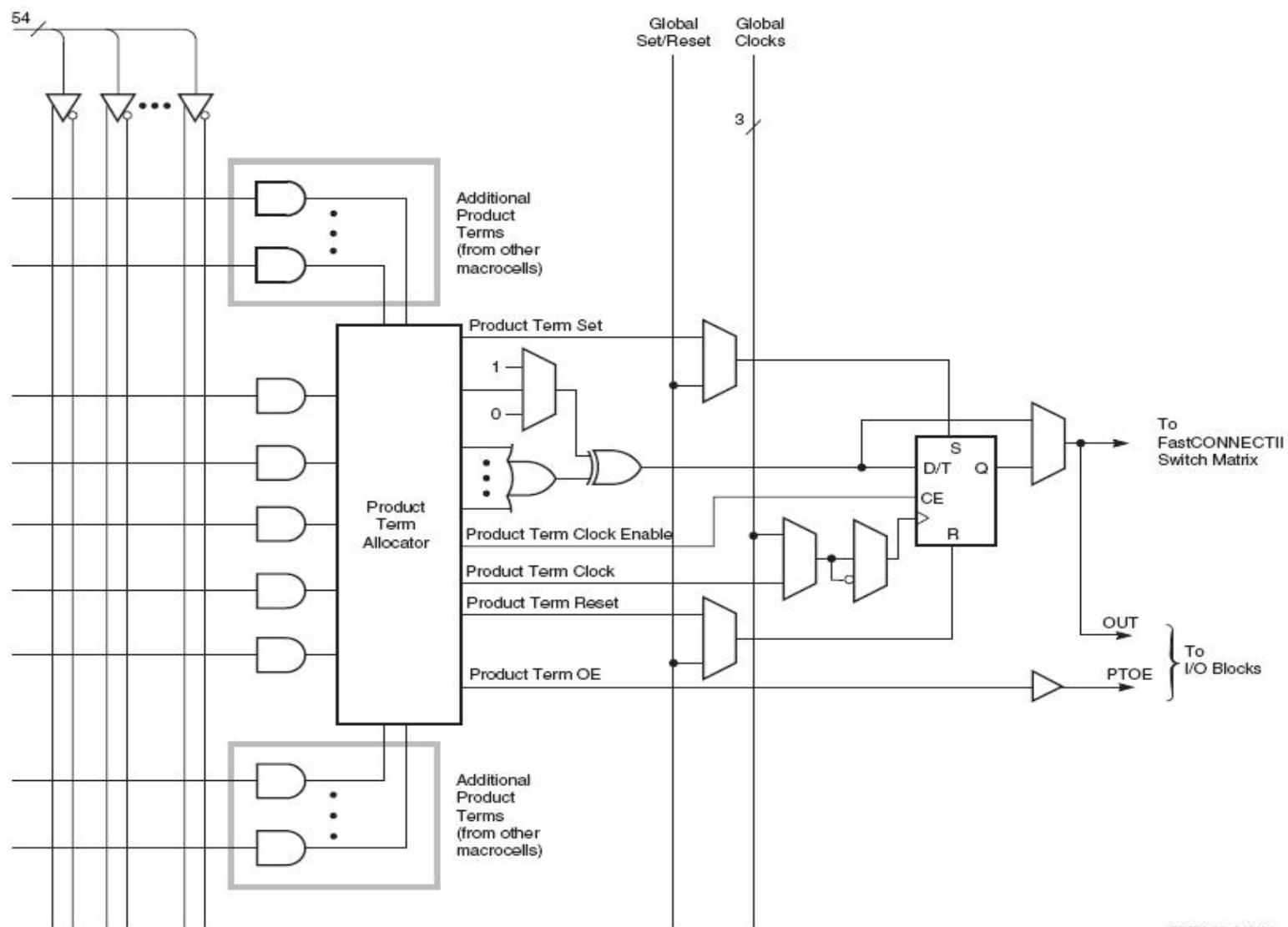
Bloque Fonctional



DS054_02_042101

Figure 2: XC9500XL Function Block

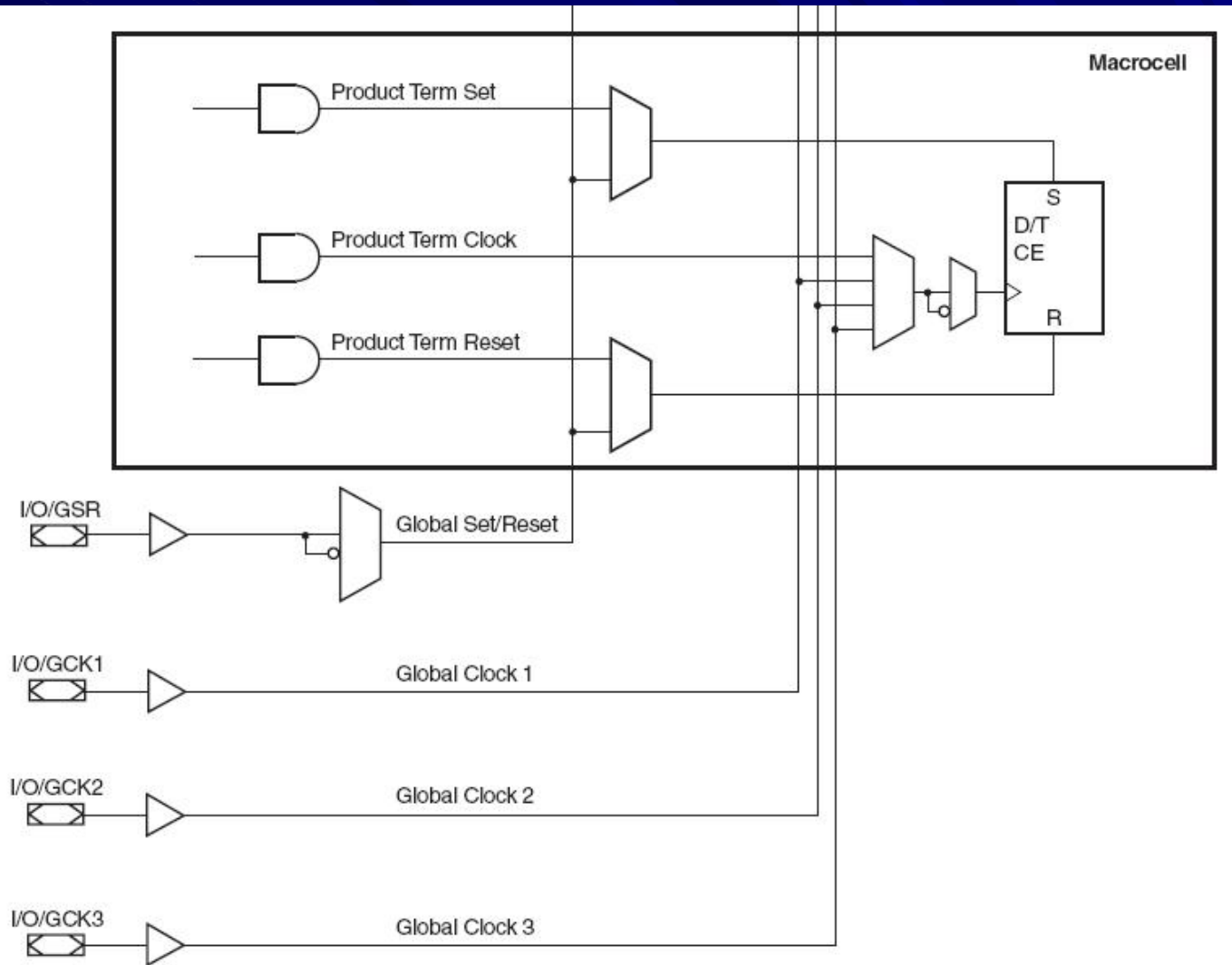
Macrocell



DS064_03_042101

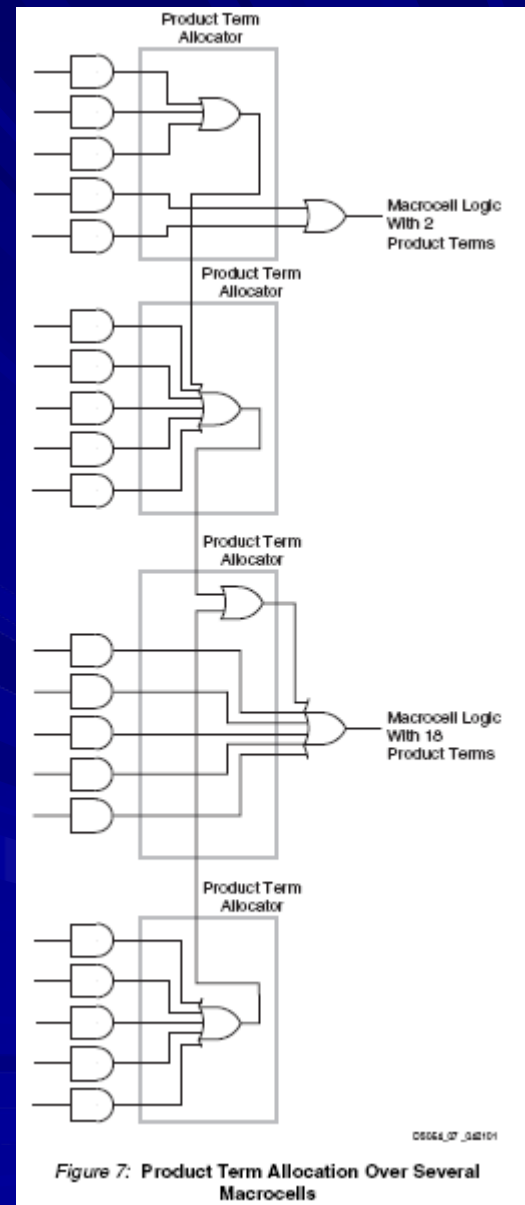
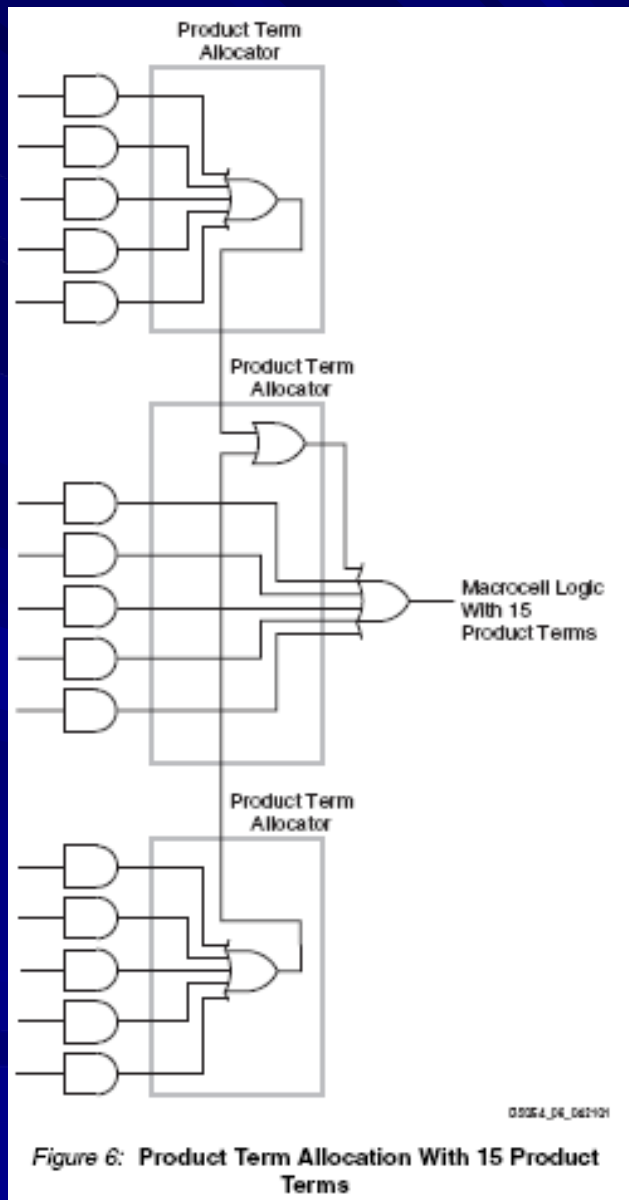
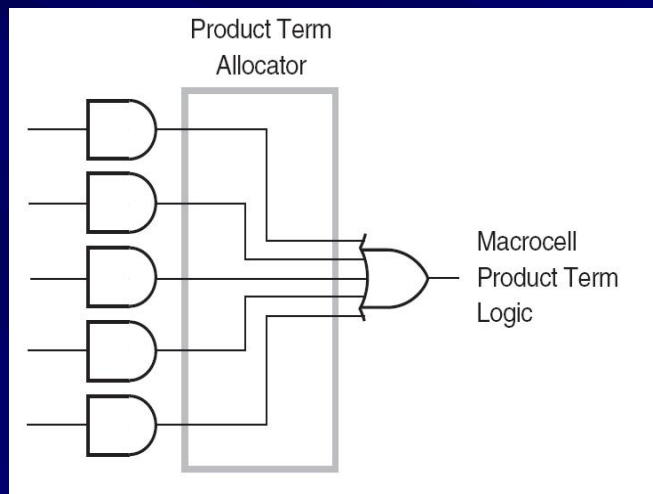
Figure 3: XC9500XL Macrocell Within Function Block

Circuito SET-RESET

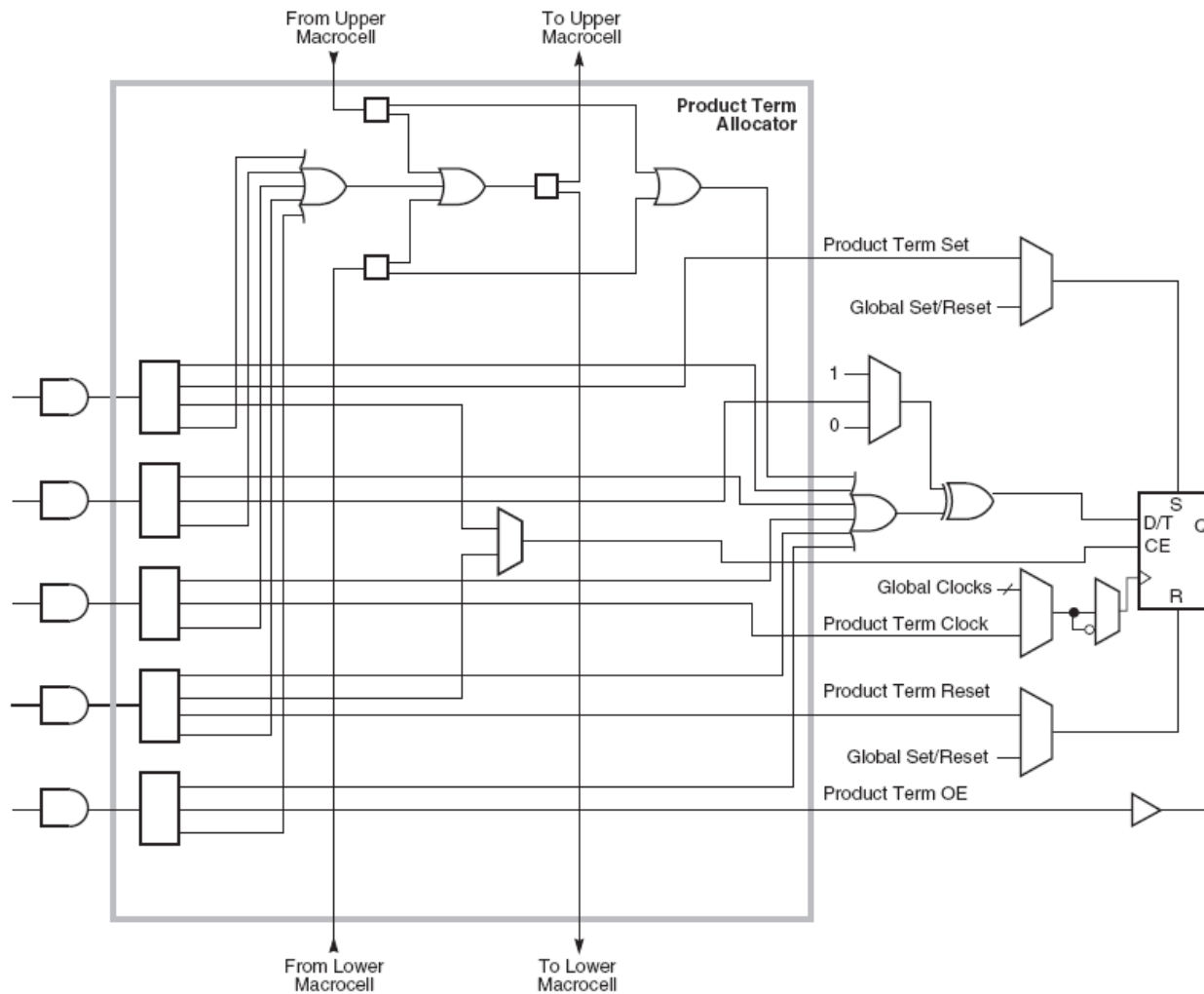


DS064_04_052209

Figure 4: Macrocell Clock and Set/Reset Capability



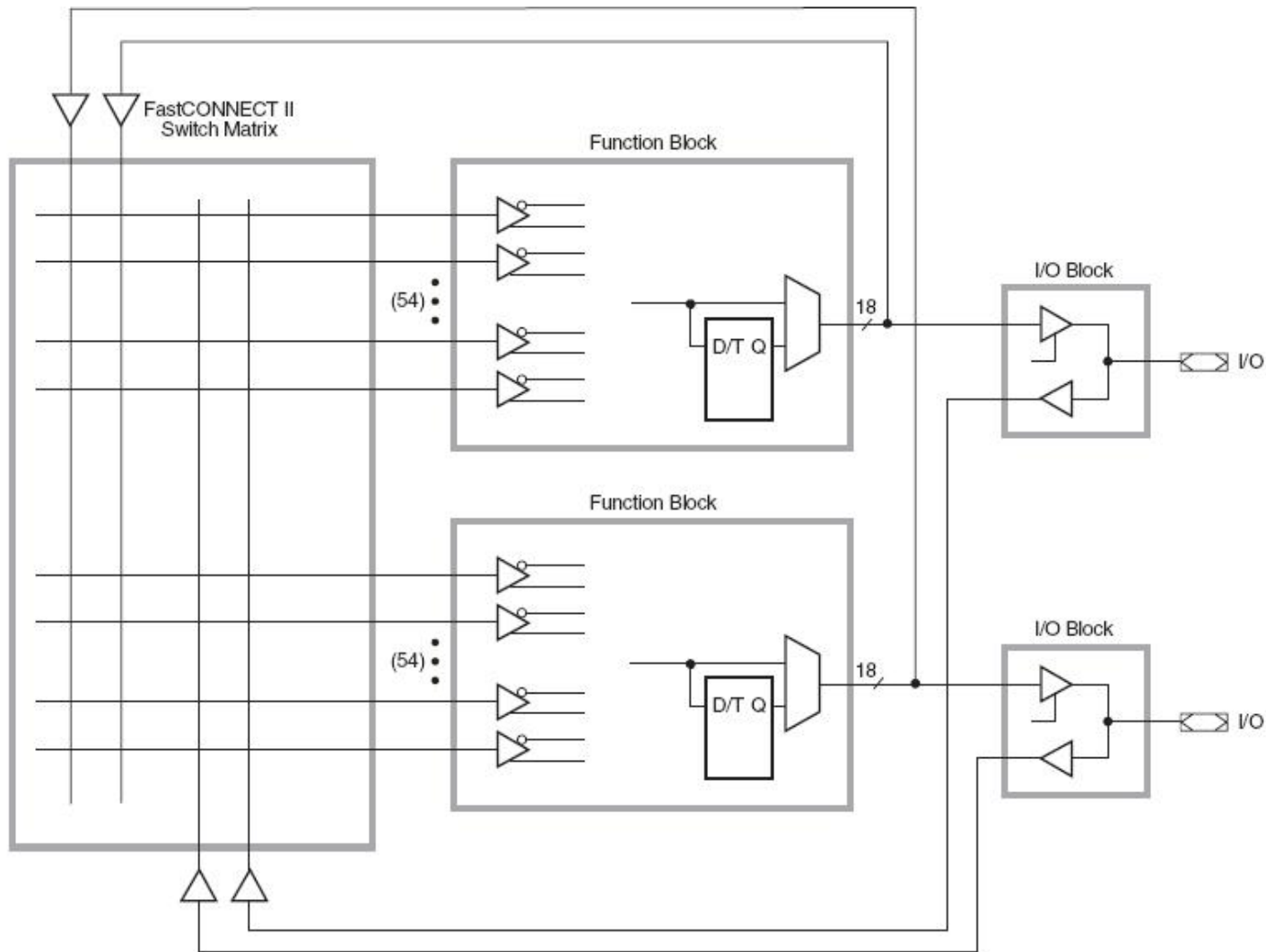
Lógica



DS054_08_042101

Figure 8: Product Term Allocator Logic

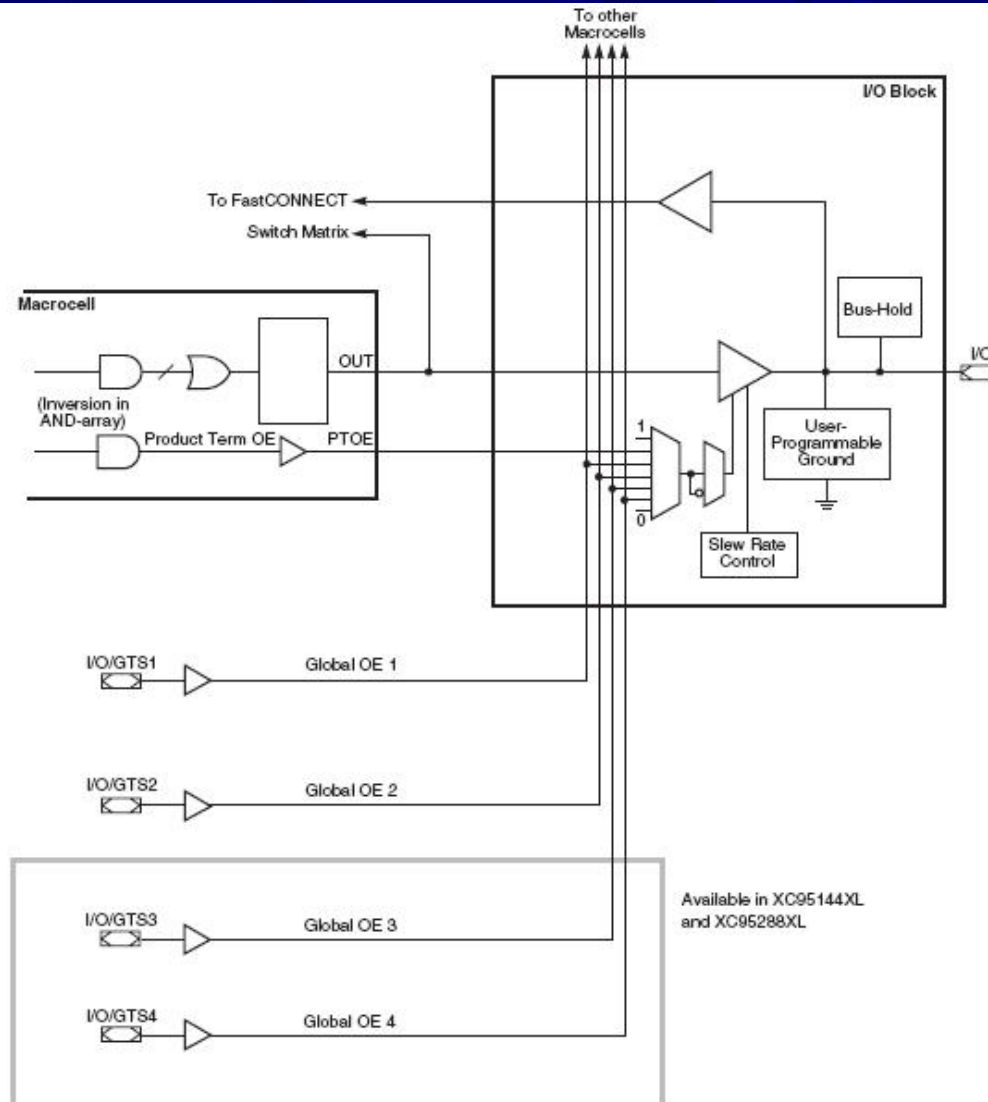
Matriz de interconexión



DS054_09_042101

Figure 9: FastCONNECT II Switch Matrix

Bloque de I/O

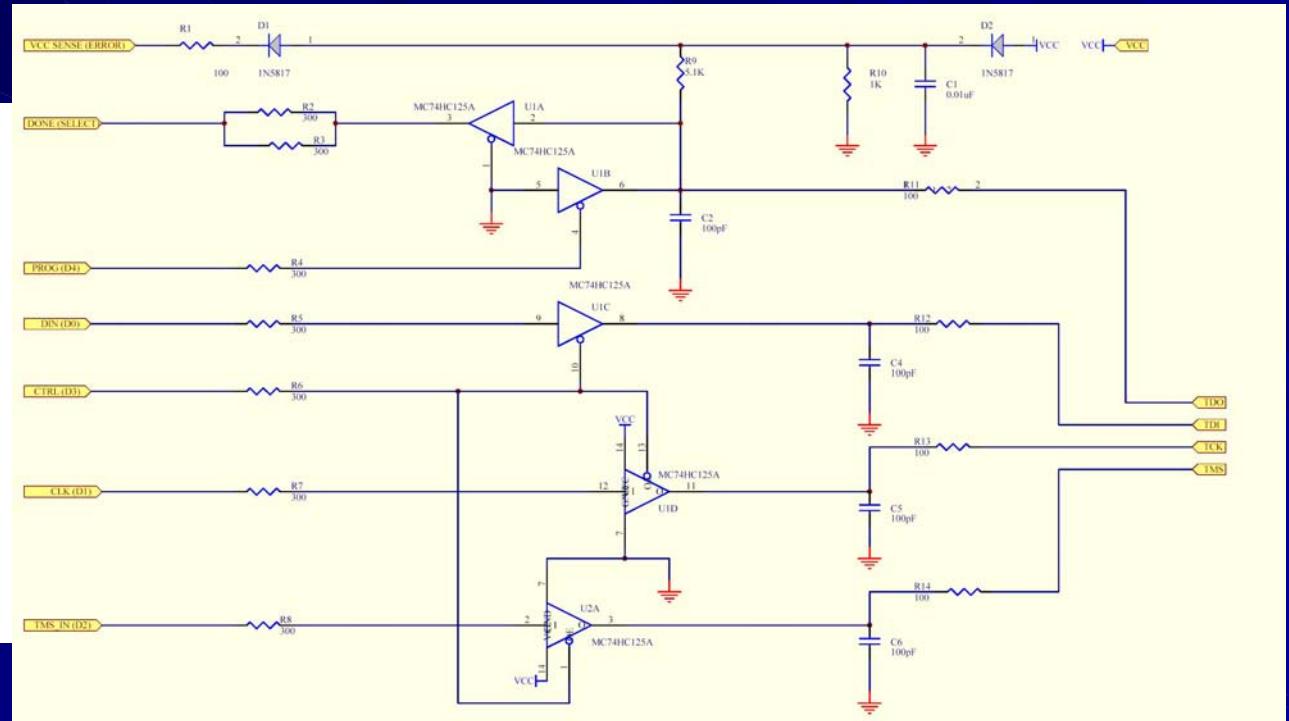
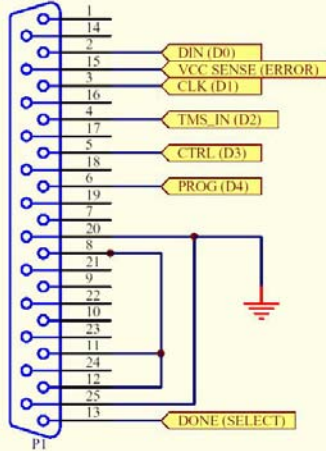


DS204_10_042101

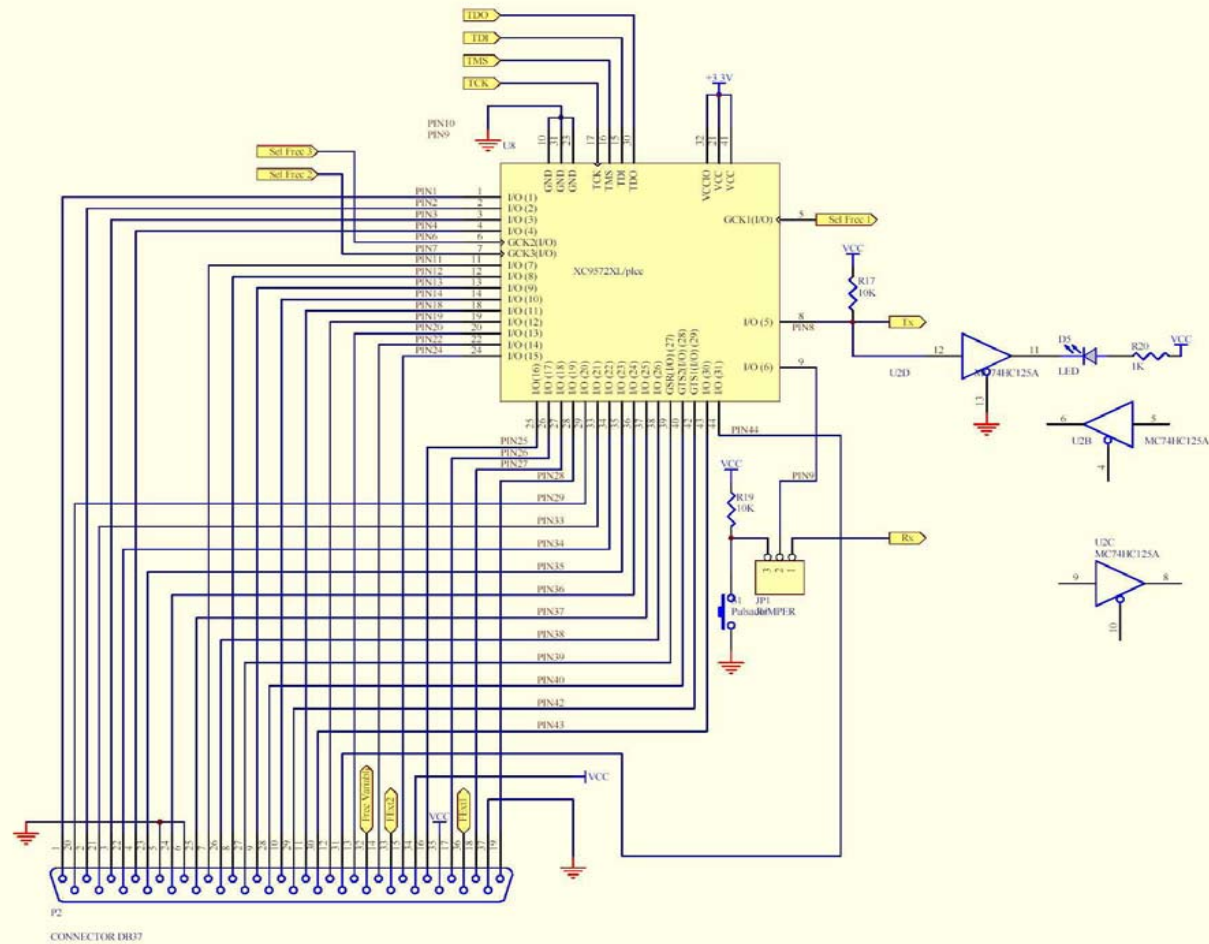
Figure 10: I/O Block and Output Enable Capability

Puerto de grabación

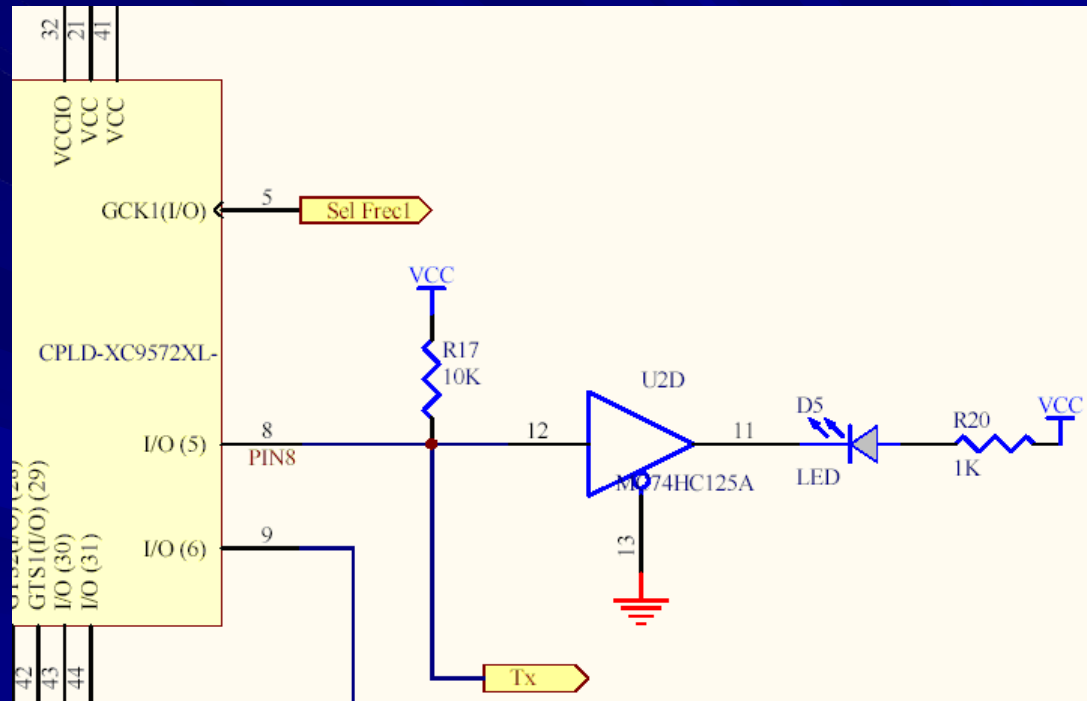
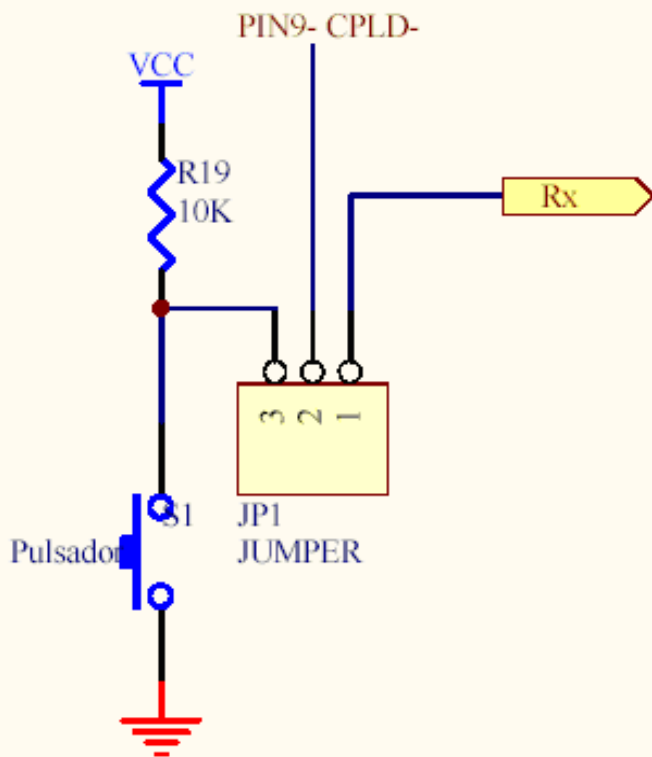
CONNECTOR DB25



Circuito CPLD



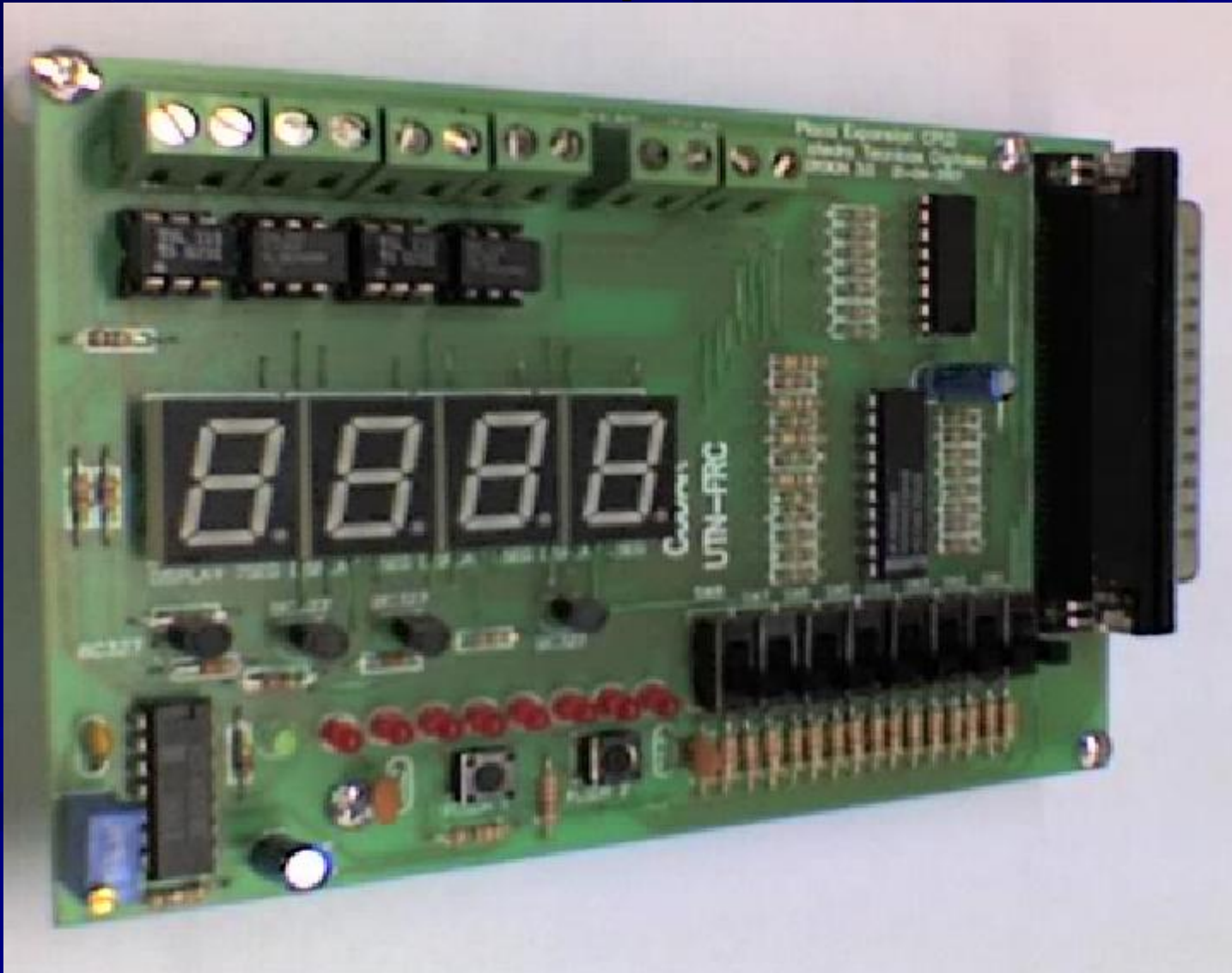
Circuito de Prueba



UCF

```
#PACE: Start of Constraints generated by PACE
#PACE: Start of PACE I/O Pin Assignments
NET "clk1" LOC = "P5" ;
NET "clk2" LOC = "P7" ;
NET "clk3" LOC = "P6" ;
NET "led_tx_prog" LOC = "P8" ;
NET "leds<0>" LOC = "P1" ;
NET "leds<1>" LOC = "P2" ;
NET "leds<2>" LOC = "P3" ;
NET "leds<3>" LOC = "P4" ;
NET "leds<4>" LOC = "P11" ;
NET "leds<5>" LOC = "P12" ;
NET "leds<6>" LOC = "P13" ;
NET "leds<7>" LOC = "P14" ;
#NET "pulsador1" LOC = "P27" ;
#NET "pulsador2" LOC = "P33" ;
NET "pulsador_rx_prog" LOC = "P9" ;
```

Placa Expansión



Display

